

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	BSC011N03LSI	**Issued**	29. June 2015
MA#	MA001010846		
Package	PG-TDSON-8-7	**Weight***	118.96 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.009	0.85	0.85	8485	8485
leadframe	non noble metal	iron	7439-89-6	0.038	0.03		318	
	inorganic material	phosphorus	7723-14-0	0.011	0.01		95	
	non noble metal	copper	7440-50-8	37.762	31.72	31.76	317425	317838
wire	noble metal	gold	7440-57-5	0.044	0.04	0.04	374	374
encapsulation	organic material	carbon black	1333-86-4	0.087	0.07		729	
	plastics	epoxy resin	-	6.156	5.18		51751	
	inorganic material	silicondioxide	60676-86-0	37.112	31.20	36.45	311962	364442
leadfinish	non noble metal	tin	7440-31-5	1.470	1.24	1.24	12355	12355
plating	noble metal	silver	7440-22-4	0.166	0.14	0.14	1391	1391
solder	noble metal	silver	7440-22-4	0.036	0.03		305	
	non noble metal	tin	7440-31-5	0.029	0.02		244	
	non noble metal	lead	7439-92-1	1.387	1.17	1.22	11658	12207
heatspreader	non noble metal	iron	7439-89-6	0.011	0.01		95	
	inorganic material	phosphorus	7723-14-0	0.003	0.00		29	
	non noble metal	copper	7440-50-8	11.320	9.52	9.53	95156	95280
heat sink CLIP	non noble metal	iron	7439-89-6	0.022	0.02		188	
	inorganic material	phosphorus	7723-14-0	0.007	0.01		56	
	non noble metal	copper	7440-50-8	22.292	18.74	18.77	187384	187628
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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